

The examined claims, i.e., Claims 1, 3-5, 8, 9, 18, 19 and 27-29 stand rejected under 35 U.S.C. §112, first paragraph, for 1) allegedly failing to comply with the enablement requirement, and 2) allegedly failing to comply with the written description requirement. These rejections are respectfully traversed.

The rejections set forth under 35 U.S.C. §112, first paragraph, are based on two separate grounds. The first ground being that Applicants do not adequately explain the composition and structure of the support frame recited in the claims. The second ground underlying the rejections is that the specification does not adequately describe how an ultrasonic soldering iron operates to deposit an indium paste to form an indium film.

#### SUPPORT FRAME

As recognized in the Office Action, the “first member” set forth in the claims corresponds to the support frame 86 shown, for example, in Figure 1. Initially, it is respectfully submitted that the composition and structure of the support frame is not an essential part of Applicants’ invention, as the claims are directed to a method for manufacturing an airtight container featuring a step of bonding the support frame 86 to a faceplate 82. Secondly, it is respectfully submitted that one skilled in the art would be readily able to determine an appropriate composition and structure of the support frame. Glass, for example, is a conventional component of a support frame, and M.P.E.P. §2164.08 and §2164.05(a) permit the specification to omit details of known elements. In any event, paragraph [0159] of the subject specification infers that the support frame 86 is made of glass, as the underlayer 204 of silver

paste is a porous film said to have a high adhesion to glass. Moreover, the Examiner's attention is respectfully directed to U.S. Patents No. 5,734,224 (see support frame 3) and No. 5,952,775 (see outer frame 8) as demonstrating that glass is a common material used for a support frame.

Accordingly, it is respectfully submitted that providing a support frame of glass or some other conventional material would be readily apparent to one skilled in the art. It is further submitted that the specification describes the support frame in such a way as to enable one skilled in the art to make or use the invention and to convey to one skilled in the art that the Applicants had possession of the claimed invention at the time the application was filed.

#### ULTRASONIC SOLDERING IRON

With respect to the contention that the specification is lacking a description of how an ultrasonic soldering iron can operate to deposit the indium paste to form an indium (In) film, it is respectfully submitted that such an operation is conventional, *per se*, and would be readily known and understood by one skilled in the art. Figure 16 illustrates the indium film being applied to the underlayer 204 by the ultrasonic soldering iron, in which the soldering iron is placed in contact with the indium film and melts the film by the application of heat. As is conventional, the soldering iron spreads the melted In film over the underlayer, unlike a squeegee which would more likely remove the melted film. As further evidence of Applicants' contention that use of an ultrasonic soldering iron, *per se*, is readily known in the art, the Examiner's attention is respectfully directed to U.S. Patents No. 5,948,165, No. 5,179,071, and No. 4,385,938 for the disclosure of using an ultrasonic soldering iron. Accordingly, it is respectfully

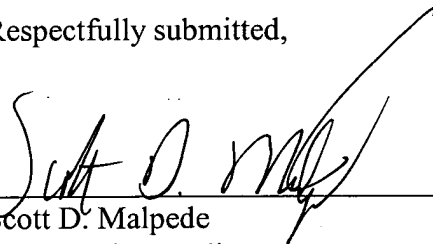
submitted that Applicants' specification fully complies with the enablement and written description requirement of providing an In film on underlayer 204.

Accordingly, reconsideration and withdrawal of the rejections of the claims under 35 U.S.C. §112, first paragraph, is respectfully requested. Further, as no art has been applied to these claims, it is respectfully submitted that the independent Claims 1, 3 and 27 are patentable over the cited art, as are all of the dependent claims, i.e., Claims 2, 4-26, 28 and 29.

In view of the foregoing, reconsideration and allowance of this application is deemed to be in order and such action is respectfully requested.

Applicants' undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,

  
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